ABSTRACT

A method for producing a processed semiconductor substrate (1), the method including: a step of preparing a laminate including a semiconductor substrate (1), a support substrate (4), an adhesive layer (2) provided between the semiconductor substrate (1) and the support substrate (4), and a release agent layer (3) provided between the semiconductor substrate (1) and the support substrate (4); a processing step of processing the semiconductor substrate (1) in the laminate; an irradiation step of irradiating the release agent layer (3) with ultraviolet laser after the processing step; and a separation step of separating the processed semiconductor substrate (1) and the support substrate (4) from each other after the irradiation step, wherein the adhesive layer (2) is formed of an adhesive composition containing an adhesive component, and an irradiation area in the irradiation step is smaller than an area of the adhesive layer (2).

FIG. 1